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MATERIAL:

HOUSING: L.C.P. (HIGH TEMP THERMOPLASTIC)
UL 94V-0, NATURAL.
CONTACT: COPPER ALLOY.

?

Δ FINISH: CONTACT AREA: 0.0002 MIN GOLD ON
0.0013 MIN ALL OVER NICKEL.
SOLDERING AREA: 0.002 MIN MATTE TIN.

3. POSITION SERIES: SEE TABLE.

4. CONN STACK HEIGHT COMBINE OF PLUG "Y"H VS REC "X"H.
STACK HEIGHT = Y + X - 5

5

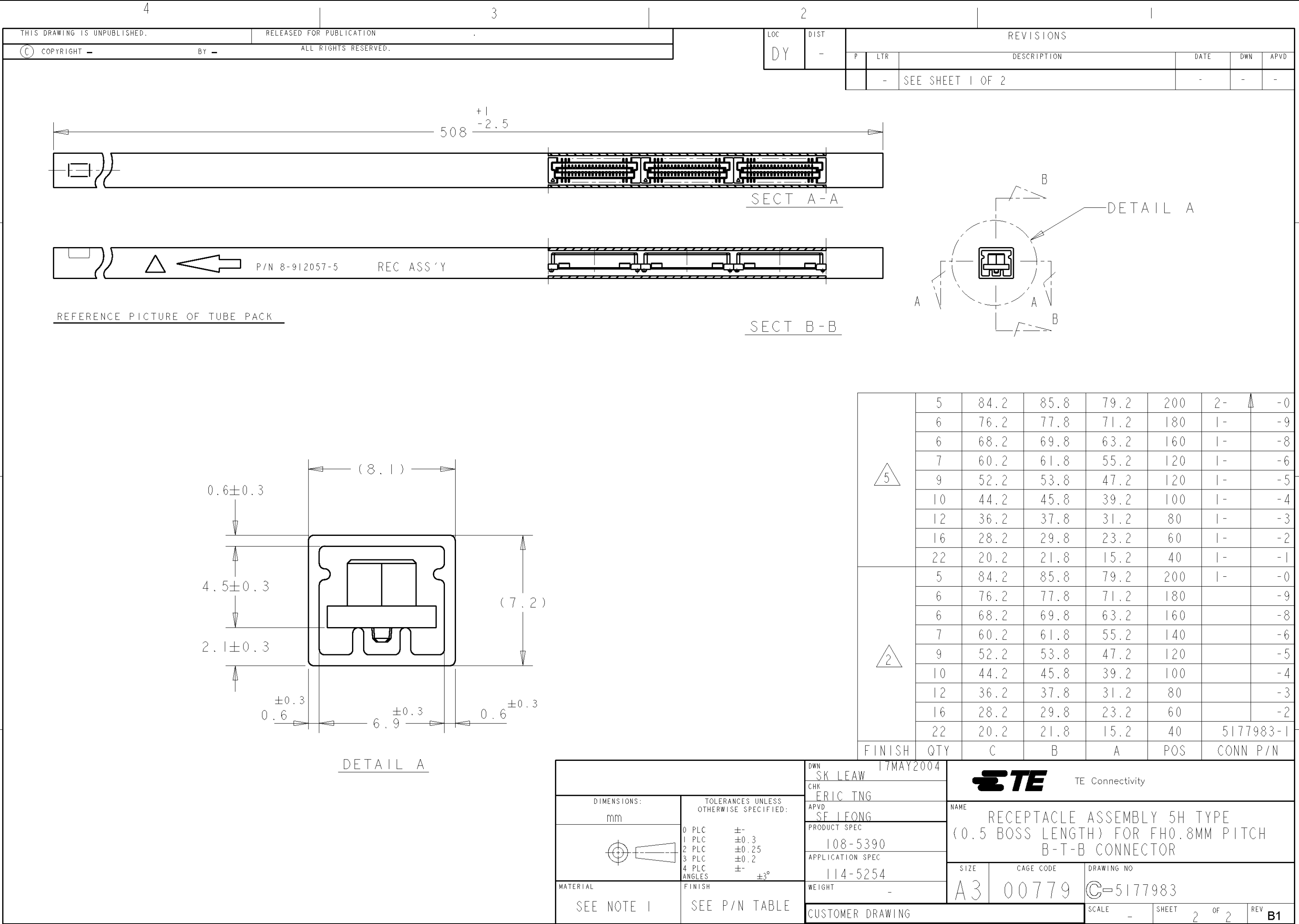
Δ FINISH: CONTACT AREA: 0.00038 MIN GOLD ON
0.0013 MIN ALL OVER NICKEL.
SOLDERING AREA: 0.002 MIN MATTE TIN.

6

DATE CODE MARKING.

P/N SEE SHEET 2 OF 2.

AMP 1470-19 REV 09MAY94



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